

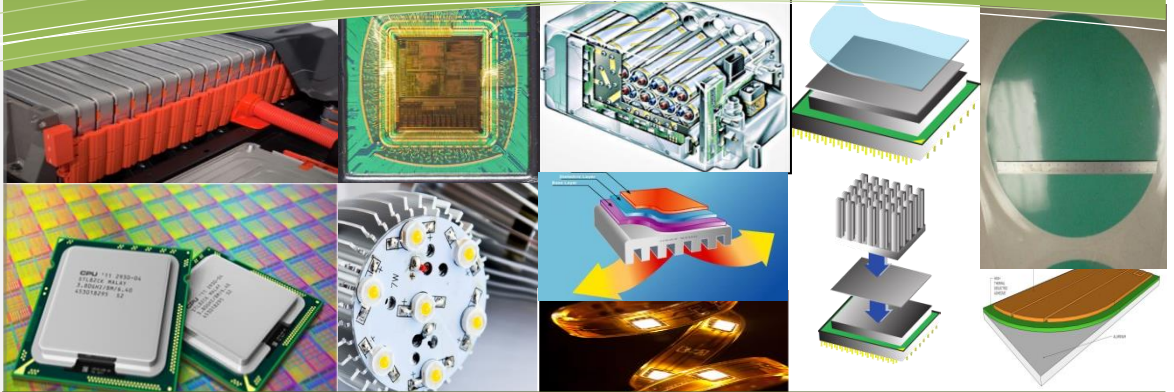
About AI Technology, Inc.

Since pioneering the use of flexible epoxy technology for microelectronic packaging in 1985, AI Technology has been one of the leading forces in development of advanced material and adhesive solutions for electronic interconnection and packaging for various industries.

The company has an ISO9001:2000 certified manufacturing and R&D facility on a 16-acre campus in Princeton Junction, NJ. AIT consists of a team of experienced and dedicated engineers, scientists and service staff to offer optimized material solutions with ultimate reliability.

AI TECHNOLOGY, INC. IS SPECIALIZED IN MANUFACTURING ADVANCED FLEXIBLE POLYMER BASED ADHESIVES

AND MATERIALS WITH DESIGNED ELECTRICAL, THERMAL & MECHANICAL PROPERTIES. SINCE 1985, SERVING ELECTRONICS, SEMICONDUCTOR, MILITARY, AERO-SPACE, MEDICAL AND AUTOMOTIVE INDUSTRY.



AIT SOLUTIONS

DIE-ATTACH ADHESIVES

Films

- ESP7660-HK 10um (Electrically Insulating but No Thermal)
- ESP7665-FP 20um (Thermally Conductive and Electrically Insulating)
- ESP8860-FP 20um (Electrically and Thermally Conductive)
- ESP8660-HK 20um and up (Electrically and Thermally Conductive)

Pastes

- ME8456 (Silver filled, electrically conductive, very high thermal conductivity)
- ME7158 (Aluminum nitride filled, electrically insulating, high thermal conductivity)
- ME7159 (Diamond filled, high electric strength, high thermal conductivity)

THERMAL INTERFACE MATERIALS – (Silicone Free)

Electrically Conductive and/or Non-Conductive

- Thermal Greases/Electro Greases
- Thermal Gels
- Thermal Adhesive Tapes
- Compressible Phase-Change Pads
- Conformable Thermal Gap Fills
- Conductive Flexible Thermal Adhesives

HIGH TEMPERATURE ADHESIVES – (up to 300C)

- High Temperature Film Adhesives
- High Temperature Paste Adhesives
- Electrically Conductive or Electrically Insulating,
- High Thermal Conductivity, High Temperature Tg

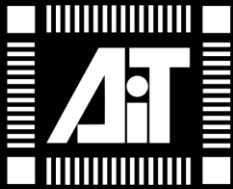
TEMPORARY WAFER PROCESSING ADHESIVE

Liquid Wax for Spin Coating and Films

- (WPA-TS 330-L, WPA-TS-330-F)
- (WPA-TL-330-L, WPA-TL-330-F)
- (WPA-TS-320-L, WPA-TS-320-F)

TAPES AND WAXES

- Wafer and Substrate Grinding Releasable Tapes
- Wafer and Substrate Grinding IPA Soluble Wax Films and Pastes
- UV and Thermal Release Dicing Tapes
- High Temperature Dicing Tapes
- Masking Tapes
- Transfer Tapes
- Thermoplastic PSA Tapes
- Insulating Tapes



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ADHESIVES AND MATERIALS WITH DESIGNED ELECTRICAL, THERMAL & MECHANICAL PROPERTIES. SINCE 1985, SERVING ELECTRONICS, SEMICONDUCTOR, MILITARY, AERO-SPACE, MEDICAL AND AUTOMOTIVE INDUSTRY.

Key Solutions:

- ME7150
- ME7155
- ME7158
- ME7159
- ME7660
- ME8412
- ME8456
- ME8512
- MC7880
- MC7883
- MC7883-UF
- MC8880
- TC8750
- TC8750-F6-B5
- TK7756
- TK7758
- TK7759
- CXP7660
- CXP8880
- ESP7355-MR
- ESP7450-HF
- ESP7456-HF
- ESP7660
- ESP7675
- ESP7679-LB
- ESP8450
- ESP8550-MR
- ESP8660
- ESP8680-HF
- LESP7675-HF
- LESP8660-HK
- HPCR080
- RTC8750
- RTK7556
- RTK7658
- RTK7659
- TP7208
- TP8090
- BGF7090
- BGL7080
- CB7078
- CB7208-EDA2
- CB8203-EDA
- CGL7018-MR
- CGR7016
- CGR7018
- CGR8010-XT
- COOL SILVER PAD
- COOL SILVER G4
- CP7178
- CP7508
- CP8503-HF
- CPR7158
- ELGR8501

ADHESIVE PASTES

Epoxy Based:

- 1-Part Epoxy Pastes for Applications like: LED Die Attach, Opto Clad, Prima-Bond, Cool Bond, Etc.
- 2-Part Epoxy Pastes for Applications like: Potting, Printable Coating, Prima Solder, Cool Bond, Etc.
- Humidity Resistance Epoxy

Cyanate Ester Based:

- 1-Part Cyanate Ester Pastes for Applications like: Glob-Tops, High Temp Die Attach, Prima-Bond, Under-fills,

ADHESIVE FILMS

- Tack and Tack-Free Films
- Die Cut to Customer Specifications
- Dry Films for Applications like: High Insulation, Flexible Die Attach, Pre-Preg, Couplers, Etc.
- Flexible Soldering Adhesive Film with Defined Bond Line Thickness using Spacers
- High Temperature High Tg Adhesive for Power Electronics in Harsh Environments; Oil & Geothermal Wells and Down Hole Applications
- Temporary Bonding Adhesive Film (Skipping Spin-coating Step)
- Cyanate Ester based for Applications like: Flip Chip Under-fills, High Temp Film Adhesive, B-Staged Die Attach, Wafer Film Adhesive, Etc.

GLOB-TOP AND UNDERFILLS

- High Temperature Glob-Tops (High Thermal Conductivity)
- High Temperature Under-fills (High Thermal Conductivity)

SUBSTRATE AND COMPONENT ATTACH ADHESIVES

- Large Area Flexible and Stress Relief Films or Paste Adhesives (High Thermal Conductivity)
- High Temperature Substrate Attach Film and Paste Adhesives

COATINGS

- Conformal Electronic Circuit Board Protective Coatings
- UV Transparent, UV Protection, Salt Water-Fog; Water-Moisture Protection
- Anti-Static Coatings: UV and/or Moisture-Water Protection

ELECTROMAGNETIC SHIELDING AND ABSORBING MATERIALS

- Conductive and Semi-Conductive Caulks, Adhesive and Coatings
- EMI Blocking-Absorbing Materials

COUPLER™, PRE-PREGS & INSULATED METAL THERMAL SUBSTRATES

- Cyanate Ester based
- Dry Film based
- Tack Film based

PRINTABLE AND DISPENSIBLE PHASE CHANGE

- (LCPR7155-LB, LCPR7154, LCPR7158, LCPR8503)

SPECIALTY APPLICATIONS MATERIAL SOLUTIONS

- Z-Axis Anisotropic Conductive Film and Paste Adhesives
- Flip-Chip Conductive Bump Adhesives
- Lid-Sealing Film and Paste Adhesives
- Optical Transparent Adhesives and Coatings (Dry, UV-Cure, 2-Part Pastes or UV Cure Pastes)
- Solar Thermal Back sheet and UV Transparent Coatings
- Conductive Sheet Gaskets
- High Temp Labels
- Antistatic Pads

NASA-ESA AND MIL-STD QUALIFIED MATERIALS

- Most AIT products will meet NASA outgassing requirement.